

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6765268

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	JOSHUA WINDMILLER	03/21/2018
	JARED RYLAN TANGNEY	03/21/2018
RECEIVING PARTY DATA		
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City:	SAN DIEGO	
State/Country:	CALIFORNIA	
Postal Code:	92121	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	17349234	
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ATTORNEY DOCKET NUMBER:	EYZ-017C1	
NAME OF SUBMITTER:	MICHAEL CATANIA	
SIGNATURE:	/Michael Catania/	
DATE SIGNED:	06/16/2021	
Total Attachments: 3		
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ASSIGNMENT

WHEREAS, **Joshua Windmiller** of Del Mar, California, and **Jared Rylan Tangney** of Encinitas, California (hereinafter referred to as “ASSIGNOR”) have invented and own a certain invention entitled “*Heterogeneous Integration Of Silicon-Fabricated Solid Microneedle Sensors And CMOS Circuitry*”, for which **United States Provisional Patent Application 62/492142** was filed on April 29, 2017, and for which a United States Non-Provisional Patent Application is sought.

WHEREAS, **Biolinq, Inc.**, a Delaware corporation having its principal place of business at 6191 Cornerstone Court East, Suite 109, San Diego, California 92121 (hereinafter referred to as “ASSIGNEE”), would like to acquire the exclusive right, title and interest in, to and under said invention and in, to and under any Letters Patent or similar legal protection to be obtained therefore in the United States of America, its territorial possessions and in any and all countries foreign thereto.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR hereby sells, assigns, transfers and sets over unto said ASSIGNEE, its successors and assigns, the full and exclusive right title and interest to said invention and to all Letters Patent claiming priority to United States Provisional Patent Application 62/492142, or similar legal protection in the United States of America, its territorial possessions and in any and all countries foreign thereto, to be obtained for said invention by said application or any continuation, division, renewal, substitute, reissue or reexamination thereof or any legal equivalent thereof in a foreign country for the full term or terms for which the same may be granted, including all priority rights under the International Convention; and ASSIGNOR hereby authorizes and requests the Commissioner of Patents to issue said Letters Patent and any legal equivalent thereof to said ASSIGNEE, its successors and assigns, in accordance with this Assignment.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

ASSIGNOR further covenants that ASSIGNEE will, upon request of ASSIGNEE, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or legal proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its designated legal representative any and all papers, instruments, declarations or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof in any foreign country which may be necessary or desirable to carry out the purposes thereof.

Assignment
*Heterogeneous Integration Of Silicon-Fabricated
Solid Microneedle Sensors And CMOS Circuitry*

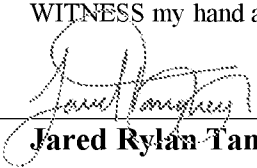
WITNESS my hand at San Diego, CA, USA, this 21 day of March, 2018.
(location)

Joshua Windmiller
Joshua Windmiller

WITNESSED: By: Thorsten Kohm Date: 21 March, 2018

Assignment
*Heterogeneous Integration Of Silicon-Fabricated
Solid Microneedle Sensors And CMOS Circuitry*

WITNESS my hand at San Diego, this 21 day of March, 2018.
(location)



Jared Rylan Tangney

WITNESSED: By: Thorsten Kohm Date: 21 March, 2018